Pro2 Series Technical Specifications

Raise3D Pro2 Series are dual extruder 3D printers with high-resolution, for manufacturing and rapid-prototyping projects of varying sizes. They are designed to print complex parts, support a variety of filaments and improve print speed, and recognized as the benchmark and gold standard for serious 3D printing applications and 24/7 reliability.

Printer	Raise3D Pro2		Raise3D Pro2 Plus	
Build Volume (W × D × H)	Single Extruder Print	Dual Extruder Print	Single Extruder Print	Dual Extruder Print
	305 × 305 × 300 mm (12 × 12 × 11.8 inch)	280 × 305 × 300 mm (11 × 12 × 11.8 inch)	305 × 305 × 605 mm (12 × 12 × 23.8 inch)	280 × 305 × 605 mm (11 × 12 × 23.8 inch)
Machine Size (W × D × H)	620 × 590 × 760 mm (24.4 × 23.2 × 29.9 inch)		620 × 590 × 1105 mm (24.4 × 23.2 × 43.5 inch)	

Weight	Net Weight	Gross Weight (Carton Only)	Gross Weight (Carton with Pallet)	Net Weight	Gross Weight (Carton Only)	Gross Weight (Carton with Pallet)
	49.9 kg (110.1 lbs)	61.4 kg (135.4 lbs)	68.9 kg (151.9 lbs)	59.5 kg (131.2 lbs)	72.7 kg (160.3 lbs)	80.2 kg (176.9 lbs)

Electrical		
	Power Supply Input	100-240 V AC, 50/ 60 Hz 230 V @ 3.3 A
	Power Supply Output	24 V DC, 600 W

General		
	Print Technology	Fused Filament Fabrication (FFF)
	Print Head System	Dual-head with Electronic Lifting System
	Filament Diameter	1.75 mm
	XYZ Step Size	0.78125, 0.78125, 0.078125 micron
	Print Head Travel Speed	15-150 mm/s
	Build Plate	Heated Aluminum Build Plate with Magnetic Holding
	Max Build Plate Temperature	110℃
	Heated Bed Material	Silicone
	Build Plate Leveling	Pre-calibrated Leveling
	Filament Run-out Sensor	Available
	Layer Height	0.05-0.6 mm
	Nozzle Diameter	0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available)
	Max Nozzle Temperature	300℃
	Connectivity	Wi-Fi, LAN, USB Port, Live Camera
	Noise Emission (Acoustic)	＜50 dB (A) When Building
	Operating Ambient Temperature	15-30℃, 10-90% RH, non-condensing
	Storage Temperature	-25℃ to +55℃, 10-90% RH, non-condensing
	Filter	HEPA Filter with Activated Charcoal
	Technical Certifications	CB, CE, FCC, RoHS

Material		
	Material Type	Hyper Speed PLA/ Hyper Speed ABS/ PLA/ ABS/ ASA/ PETG/ PC/ PETG ESD/ TPU 95A/ PVA+
	Third Party Material	Supported by Raise3D OFP (Open Filament Program)*

Software		
	Slicing Software	ideaMaker
	Supported File Types	STL/ OBJ/ 3MF/ OLTP
	Supported OS	Windows/ macOS/ Linux
	Machine Code Type	GCODE

Printer Controller		
	User Interface	7-inch Touch Screen
	Network	Wi-Fi, Ethernet
	Power Loss Recovery	Available
	Screen Resolution	1024 × 600
	Motion Controller	Atmel ARM Cortex M7.400 MHZ FPU
	Logic Controller	NXP i.MX6, Quad core 1 GHz ARM processor
	Memory	1 GB
	Onboard Flash	16 GB
	OS	Embedded Linux
	Ports	USB 2.0 × 2, Ethernet × 1

*For detailed information and slicing profiles of the materials supported by Raise3D OFP, please visit https://www.ideamaker.io/.

RAISE3D